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ABSTRACT



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A grinder composed of at least a chuck table (17) having a suction region (1) and a frame (2) and grinding means (30) for grinding a semiconductor wafer (W) held on the chuck table (17) is used. When a semiconductor wafer (W) having an outside diameter D1 smaller than that of the suction region (1) is ground, a semiconductor wafer (W) protective member (3) having an outside diameter D3 larger than the outside diameter D1 of the semiconductor wafer and larger than the diameter D2 of the suction region (1) is stuck on the side not to be ground of the semiconductor wafer (W). The whole surface of the semiconductor wafer (W) is held on the suction region (1), with the semiconductor wafer protective member (3) down. The exposed surface of the held semiconductor wafer (W) is ground by the grinding means (30). Thus the edge of the semiconductor wafer (W) is prevented from breaking, chipping and cracking.